

IN THE CLAIMS

Please cancel claims 1, 2 and 7-22 without prejudice or disclaimer.

Fig. 18-27³. (Amended, now includes subject matter of claim 1)

A semiconductor device, comprising:

a conductive layer pattern ^{214a} formed on a substrate;

an inter-layer insulating film ²¹⁵ which covers said conductive layer pattern and is formed on said substrate;

a first connection hole ²¹⁶ formed in a upper layer of said inter-layer insulating film above said conductive layer pattern;

a second connection hole ²¹⁷ which reaches said conductive layer pattern from the bottom portion of said first connection hole and then has a smaller diameter than that of said first connection hole and formed on said inter-layer insulation film; and

a plug ^{218/218a} having conductivity formed in a state filling internal portions of said first connection hole and said second connection hole;

an upper insulating film ²¹⁹ formed on said inter-layer insulating film;

a third connection hole ²²⁰ which reaches said plug and is formed on said inter-layer insulating film; and

a conductive portion ²²¹ which is connected to said plug and formed in said third connection hole.

4. (Amended, contains subject matter of claims 1 and 2)

A semiconductor device, comprising:

a conductive layer pattern formed on a substrate;

an inter-layer insulating film which covers said conductive layer pattern and is formed on said substrate;

a first connection hole formed in a upper layer of said inter-layer insulating film above said conductive layer pattern;

a second connection hole which reaches said conductive layer pattern from the bottom portion of said first connection hole and then has a smaller diameter than that of said first connection hole and formed on said inter-layer insulation film; and

a plug having conductivity formed in a state filling internal portions of said first connection hole and said second connection hole;

wherein the upper surface of said plug is formed to almost the same height as the surface height of said inter-layer insulating film

an upper insulating film formed on said inter-layer insulating film;

a third connection hole which reaches said plug and is formed on said inter-layer insulating film; and

a conductive contact portion which is connected to said plug and formed in said third connection hole.